



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Serial No.: **09/029,608**

Filed: **May 15, 1998**

Group Art Unit: **2827**

Examiner: **D. Graybill**

P.T.O. Confirmation No.: **6285 J.mcmill**

For. **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

October 25, 2002

Sir:

In response to the Office Action dated **July 25, 2002**, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims ~~87-90, 117, 118, 121, 122, 124-126~~ and 128, without prejudice or disclaimer.

Please amend claims 109-112, 115, 119, 123 and 127 as follows:

109. (Twice Amended) A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed;

I | a resin layer formed on the surface of the semiconductor element so as to seal the protruding electrodes except end portions thereof; and

external connection protruding electrodes provided to the end portions of the protruding electrodes that protrude from the resin layer,

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